

KB-2150GC (ANSI : FR-2/JIS PP3F)

覆铜箔酚醛树脂纸基层压板

特点

- 气味少
- 无卤板材有利于环境保护
- 高耐漏电起痕指数 600 伏以上
- 优异的耐湿、热性
- 适合之冲孔温度为 40~70℃
- 弓曲率、扭曲率小且稳定

Features

- Less odor
- Halogen-free, Friendly to the environment.
- High CTI over 600V
- Superior heat and humidity resistance
- Suitable for punching at 40~70℃
- Warp and twist are small and stable.

General Properties 一般特性

Test Item 测试项目	Unit 单位	Test Condition 处理条件	Testing Method 测试方法	Specification 规格值	Typical Value 典型值
Solder Resistance 耐焊性 (float 260℃)	Sec	A	JIS C 6481	≥10	20~30
Heat Resistance 耐热性	—	130℃ 30min	JIS C 6481	No Change 无异常	No Change 无异常
Peel Strength (Copper Foil 35 μm) 铜箔剥离强度 (35 μm 铜箔)	kgf/cm	A float 260℃/10Sec	JIS C 6481	≥12	1.8~2.0 1.7~1.9
Flexural Strength 弯曲强度	Lengthwise 纵向	A	JIS C 6481	≥8	14~16
	Crosswise 横向			≥8	13~14
Volume Resistivity 体积阻抗系数	Ω-cm	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	5×10 ¹⁰ 5×10 ⁹	1.0×10 ¹² ~10 ¹³ 1.0×10 ¹² ~10 ¹³
Surface Resistivity 表面抗阻	Adhesive Side 粘接剂面	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	1×10 ¹² 1×10 ¹¹	1.0×10 ¹² ~10 ¹³ 1.0×10 ¹¹ ~10 ¹²
	Laminate Side 积层板面	C-96/20/65 C-96/20/65+C-96/40/90		1×10 ¹¹ 5×10 ⁸	1.0×10 ¹¹ ~10 ¹² 1.0×10 ¹⁰ ~10 ¹¹
Insulation Resistance 绝缘抗阻	Ω	C-96/20/65 C-96/20/65+D-2/100	JIS C 6481	1×10 ¹¹ 1×10 ⁸	1.0×10 ¹¹ ~10 ¹² 1.0×10 ⁹ ~10 ¹⁰
Chemical Resistance 耐化学性	—	3% NaOH 40℃ 3min 3% 氢氧化钠 40℃ 3 分钟	JIS C 6481	No change 无异常	No Change 无异常
		Boiled in trichloroethylene for 3 min 三氯乙烯中煮沸 3 分钟	JIS C 6481	No change 无异常	No Change 无异常
Moisture Absorption 吸水率	%	E-24/50+D-24/23	JIS C 6481	≤0.75	0.5~0.75
Flammability 阻燃性	Rating	A	UL94	UL94 V-0	V-0
Dielectric Constant (1 MHz) 介电常数 (1 MHz)	—	C-96/20/65 C-96/20/65+D-24/23	JIS C 6481	≤5.0 ≤5.3	3.5~5.0 4.0~5.3
Dissipation Factor 介质损耗因子	—	C-96/20/65 C-96/20/65+D-24/23	JIS C 6481	≤0.04 ≤0.05	0.025~0.035 0.030~0.045
CTI Value CTI 值	V	0.1% NH ₄ CL	IEC 60112	≥600	≥600
Punching Temperature 冲孔温度	℃	A	GB/T4722	40-70	40-70

Remarks: Typical values for reference only 注: 典型值仅作参考 Stand values according to JIS-C-6485 规格值参照 JIS-C-6485

A = Keep the specimen originally without any process 保持原样, 不作处理

C = Temperature and humidity conditioning 在恒温恒湿的空气中处理

D = Immersing in distilled water with temperature control. 浸在恒温的水中处理

E = Temperature conditioning 在恒温的空气中处理

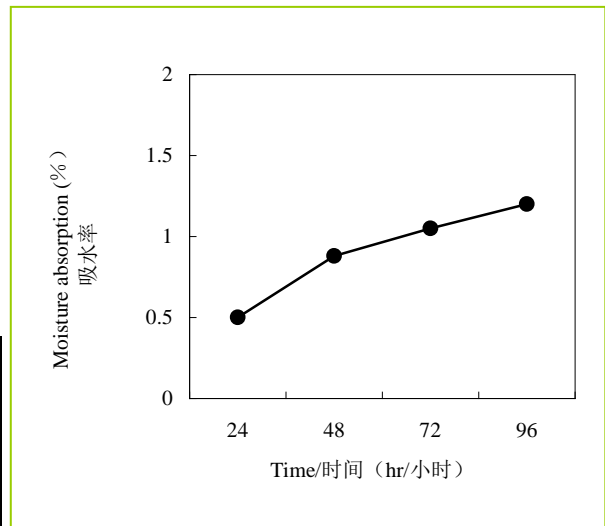
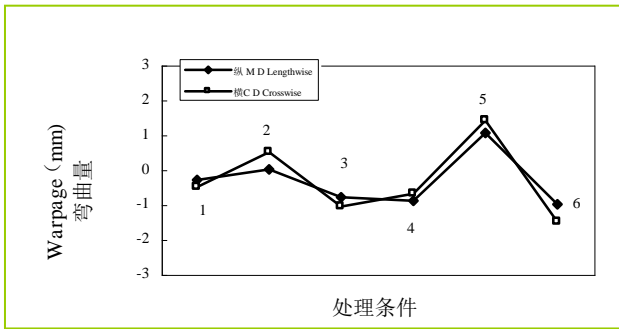
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Speciality Chart 板材特性图

Warpage of PCB during processing/印制电路板
加工时弯曲度(Thickness 1.6mm single side)

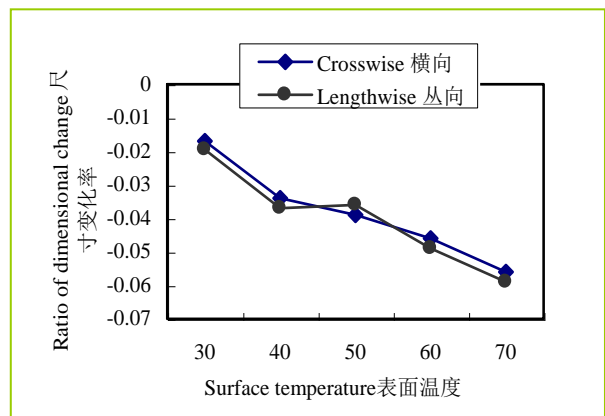
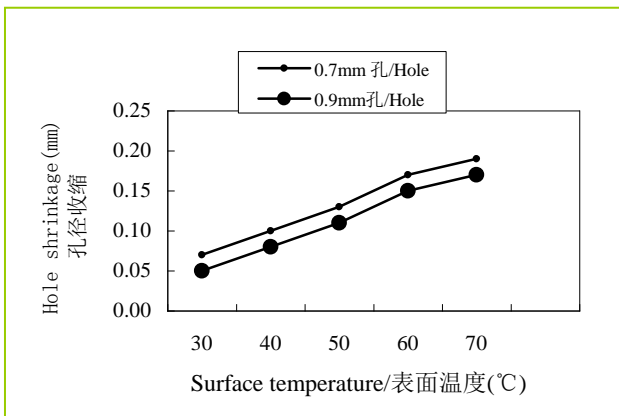
Moisture absorption 吸水率



1.Feeding 投料	2.Heating at 130°C for 90 sec 130°C下加热 90 秒	3.Etching, Rinsing, Drying 蚀刻, 清洗, 烘干
4.Heating at 200°C for 30 sec 200°C下加热 30 秒	5.Punching at 50°C 50°C下冲孔	6.Soldering at 260°C for 5sec 260°C 焊锡 5 秒

Punched hole shrinkage
冲孔后孔径收缩

Dimensional change of punched PCB
冲孔后之尺寸变化



Purchasing Information 采购信息

Type 类型	Thickness 厚度	Copper Cladding 铜箔厚度	Regular Size (mm) 常规尺寸	CTI Value CTI 值
KB-2150GC	0.8mm ~	35μm	1020*1220mm (40" * 48")	600V
FR-2	1.6mm	70μm	1020*1020mm (40" * 40")	

Note: Other sheet size and thickness could be available upon request.

可根据客户要求提供其它尺寸和厚度